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# 2.4GHz SMD On-ground Antenna

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# 2.4GHz SMD On Ground Antenna

#### 1.0 SCOPE

This Product Specification covers the mechanical, electrical and environmental performances requirements and test methods for 2.4GHz SMD on ground antenna.

# 2.0 PRODUCT DESCRIPTION

### 2.1 PRODUCT NAME AND SERIES NUMBER

2.4GHz SMD on ground antenna 47948-\*\*\*\*

### 2.2 Design and Construction

Antenna shall be of the design, construction and physical dimensions specified on the applicable sales drawing.

### 2.3 Materials

- a) Housing: Refer to respective Molex sales or engineering drawings
- b) Plating: Refer to respective Molex sales or engineering drawings

#### 3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

See drawings and other sections of this specification for the relevant reference documents. In cases where the specification differs from the drawings, the drawings take precedence.

# 4.0 RATINGS

#### 4.1 RF POWER

2 Watts

#### **4.2 TEMPERATURE**

Operating:	- 30°C to + 85°C
Storage :	- 40°C to + 85°C

#### 4.3 HUMIDITY

Storage	:	+15~70% RH
Test :		+80~95% RH

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# 5.0 PERFORMANCE

# 5.1 ELECTRICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5.1.1	Frequency Range	Measure antenna on recommended PCB through VNA E5071C	2400MHz-2483.5MHz
5.1.2	Return Loss	Measure antenna on recommended PCB through VNA E5071C	< -9 dB
5.1.3	Peak Gain	Measure antenna on recommended PCB through OTA chamber	3.0dBi
5.1.4	Avg. Total Efficiency	Measure antenna on recommended PCB through OTA chamber	>70%
5.1.5	Polarization	Measure antenna through the OTA chamber	Liner
5.1.6	Input Impedance	Measure antenna on recommended PCB through VNA E5071C	50Ohms

### 5.2 MECHANICAL REQUIREMENTS

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT		
5.2.1	Plating thickness measure	Use X-ray measure the thickness of plating	The plating thickness SPEC:Cu 12~16uM;Mid-P Ni 2~4uM;Au 0.1 ~0.2uM.		
5.2.2	Cross cut Test	Cross cut adhesion test Testing is performed in accordance with ASTM D-3359-93	acceptance criteria > 2B as acceptance, <35% peeling off.		

# **5.3 RELIABILITY REQUIREMENTS**

ITEM	DESCRIPTION	DESCRIPTION TEST CONDITION	
5.3.1	Peeling Force	Apply six axial peeling force on parts soldered on the PCB at the speed rate of 25±3 mm/minute	
5.3.2	Solderability testing	Dip solder tails into the molten solder (held at 245+-5°C for 5s)	Solder coverage: 95% Min.

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# **5.4 ENVIRONMENTAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
5.4.1	Humidity Test	1.Test condition: The device under test is kept for 12 hours in an environment with a temperature of 55 degrees and a relating humidity of 95%. Thereafter for 12 Hours in an environment with a temperature of 25 degrees and a relative humidity of 95%. The cycle is repeated until a total of 6 cycles have been completed. Hereafter the conditions are stabilized at room temperature.	<ol> <li>Parts should meet RF spec before and after test.</li> <li>No cosmetic problem</li> </ol>
5.4.2	Temperature cycling test	1.Test condition: The product temperature is decreased from room temperature to -40 degrees during 2 Hours and kept there for 2 hours. Then temperature is increased to 85 degree during 2 hours and kept for 2 hours. The temperature is then again decreased to -40 degrees during a 2-hours period. The cycle is repeated until a total of 6 cycles have been completed. Hereafter the conditions are stabilized at room temperature.	<ol> <li>Parts should meet RF spec before and after test.</li> <li>No cosmetic problem</li> </ol>
5.4.3	Salt mist test	1.Test condition: The device under test is exposed to a spray of a 5% (by volume) resolution of Nacl in water for 2 hours. Thereafter the device under test is left for 1 week in room temperature at a relative humidity of 95%. The cycle is repeated until a total of 2 cycles have been completed. Here after the conditions are stabilized at room temperature.	<ol> <li>Parts should meet RF spec before and after test.</li> <li>No visible corrosion. Discoloration accept.</li> </ol>
5.4.4	HNO3 Test	General test condition	1) No corrosion.

The meaning of text "No mechanical damage" in the table above is:

- a. no soldering problemb. no adhesion problem of glue
- c. no peel off of plating

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# 6.0 TEST GROUPINGS

INOT	Note: All test specimens (except group 5) shall pass the reflow process for 3 times.						
Test Item	Description	Group1	Group2	Group3	Group4	Group5	Group6
5.3.1	Peeling Force	Х					
5.3.2	Solderability testing		х				
5.4.1	Humidity Test			х			
5.4.2	Temperature cycling test				х		
5.4.3	Salt mist test					Х	
5.4.4	HNO3 Test						Х
	Sample Quantity	5	5	5	5	5	5

Note: All test specimens (except group 5) shall pass the reflow process for 3 times.

# 7.0 RECOMMENDED REFLOW CONDITION

